

● General Description

This silicon carbide Power MOSFET device has been developed using ZMJ's advanced 4th generation SiC MOSFET technology. The device features a very low $R_{DS(on)}$ over the entire temperature range combined with low capacitances and very high switching operations. It improves application performance in frequency, energy efficiency, system size and weight reduction.

● Features

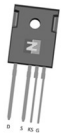
- High blocking voltage
- High speed switching with low capacitances
- Low $R_{DS(on)}$ to minimize conductive loss
- Low gate charge for fast switching
- Low thermal resistance
- 100% avalanche tested
- AEC-Q101 Qualified

● Application

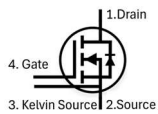
- Motor drives
- On board charger
- DC-DC
- Auxiliary drives



● Product Summary



TO-247-4 LP


 $V_{DS}=1200V$
 $R_{DS(on)}=71m\Omega$
 $I_D=30A$


● Ordering Information

Part NO.	ZMCA075R120CA
Marking	ZMC075R120
Packing information	TUBE BULK
Basic ordering unit (pcs)	450

● Absolute Maximum Ratings ($T_A=25^\circ C$, unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Max.	Unit
Drain-source voltage	V_{DS}		-	1200	V
Gate-source voltage ^①	V_{GS}	Transient Voltage	-10	25	V
	V_{GS}	Static Voltage	-10	24	V
Recommended turn on gate voltage	$V_{GS(on)}$		15	18	V
Recommended turn off gate voltage	$V_{GS(off)}$		-4	0	V
Continuous drain current	I_D	$V_{GS}=18V, T_C=25^\circ C$	-	30	A
	I_D	$V_{GS}=18V, T_C=75^\circ C$	-	25	A
	I_D	$V_{GS}=18V, T_C=100^\circ C$	-	21	A
Pulsed drain current	I_{DM}	Pulsed, $t_p \leq 10 \mu s, T_C = 25^\circ C$	-	120	A

Diode continuous current	I_S	$V_{GS}=-4V, T_C=25^{\circ}C$	-	23	A
Diode pulsed current	$I_{S,pulse}$	$V_{GS}=-4V, Pulsed, t_p \leq 10 \mu s, T_C = 25^{\circ}C$	-	92	A
Total power dissipation	P_D	$T_C=25^{\circ}C$	-	125	W
Total power dissipation	P_D	$T_A=25^{\circ}C$	-	2.4	W
Operating junction temperature	T_J		-55	175	$^{\circ}C$
Storage temperature	T_{STG}		-55	175	$^{\circ}C$
Single pulse avalanche energy	E_{AS}	$L=0.5mH, V_{GS}=18V, R_g=25\Omega,$	-	182	mJ

● Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	1.2	$^{\circ}C/W$
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	$^{\circ}C/W$
Soldering temperature	T_{sold}	-	-	260	$^{\circ}C$

● Electronic Characteristics ($T_J=25^{\circ}C$, unless otherwise specified)

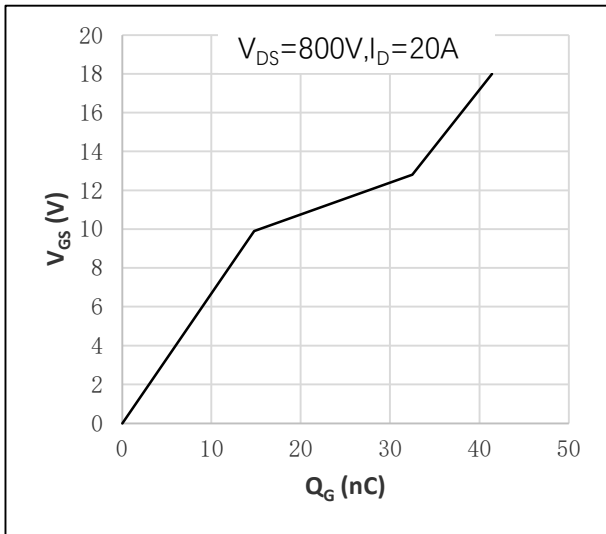
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	1200	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=5mA$	2	3	4	V
Drain-source leakage current	I_{DSS}	$V_{GS}=0V, V_{DS}=1200V$	-	-	10	μA
Gate- source leakage current	I_{GSS}	$V_{GS}=-10V, V_{DS}=0V$	-	-	-100	nA
		$V_{GS}=25V, V_{DS}=0V$	-	-	100	nA
Static drain-source on resistance	$R_{DS(ON)}$	$V_{GS}=18V, I_D=20A, T_J=25^{\circ}C$	-	71	85	m Ω
		$V_{GS}=18V, I_D=20A, T_J=175^{\circ}C$	-	116	-	m Ω
		$V_{GS}=15V, I_D=20A, T_J=25^{\circ}C$	-	94	-	m Ω
Forward transconductance	g_{FS}	$V_{DS}=10V, I_{SD}=20A$	-	26	-	S
Diode forward voltage	V_{FSD}	$V_{GS}=-4V, I_{SD}=20A$	-	4.8	5.5	V

● Dynamic characteristics ($T_J=25^{\circ}C$, unless otherwise specified)

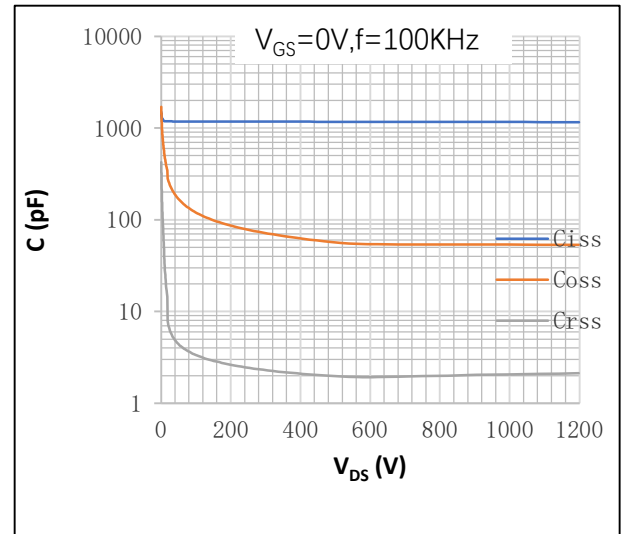
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f=100KHz, V_{DS}=800V, V_{GS}=0V$	-	1170	-	pF
Output capacitance	C_{oss}		-	54	-	pF
Reverse transfer capacitance	C_{rss}		-	2	-	pF
Output charge	Q_{oss}	$f=100KHz, V_{GS}=0V, V_{DS}=0V \text{ to } 800V$	-	71.5	-	nC
Coss stored energy	E_{oss}		-	19.6	-	μJ

Gate resistance	R_g	$f = 1\text{MHz}$	-	0.9	-	Ω
Total gate charge	Q_g	$V_{DD} = 800\text{V},$ $I_D = 20\text{A},$ $V_{GS} = -4\text{V}/18\text{V}$	-	41.4	-	nC
Gate-source charge	Q_{gs}		-	14.8	-	nC
Gate-drain charge	Q_{gd}		-	17.7	-	nC
Turn-on delay time	$t_{D(on)}$	$V_{GS}=-4\text{V}/18\text{V},$ $V_{DS}=800\text{V},$ $R_G=5\Omega,$ $I_D=20\text{A},$ $L=100\mu\text{H}$	-	64	-	ns
Turn-on rise time	t_r		-	23	-	ns
Turn-off delay time	$t_{D(off)}$		-	21	-	ns
Turn-off fall time	t_f		-	12	-	ns
Turn-on energy	E_{on}		-	864	-	μJ
Turn-off energy	E_{off}		-	112	-	μJ
Reverse recovery time	t_{rr}	$V_{DD}=800\text{V}, \text{d}I_S/\text{d}t =$ $2000\text{A}/\mu\text{s}, I_S=20\text{A}$	-	32	-	ns
Reverse Recovery Peak Current	I_{rrm}		-	8.4	-	A
Reverse recovery charge	Q_{rr}		-	197	-	μC

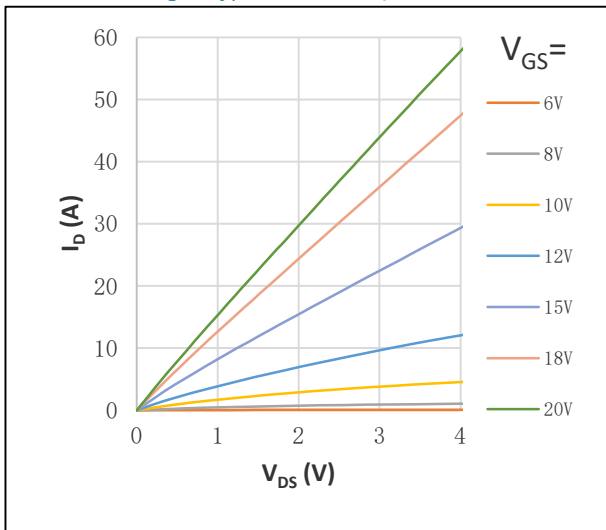
● Fig.1 Gate-source voltage as a function of gate charge; Typical values; $T_j=25^\circ\text{C}$



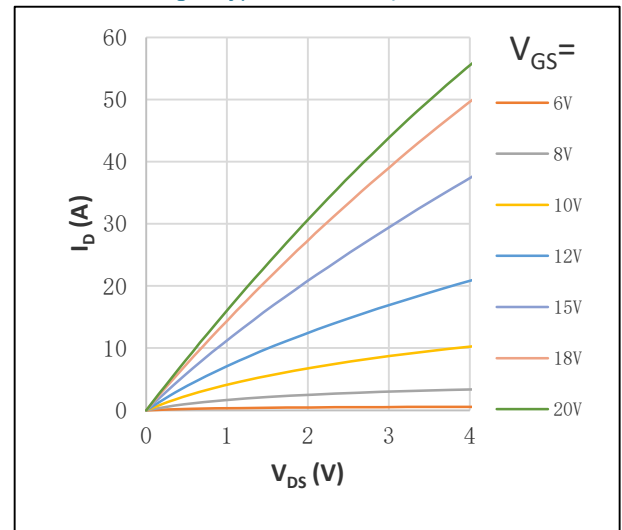
● Fig.2 Input, output and reverse transfer capacitances as a function of drain-source voltage; Typical values; $T_j=25^\circ\text{C}$



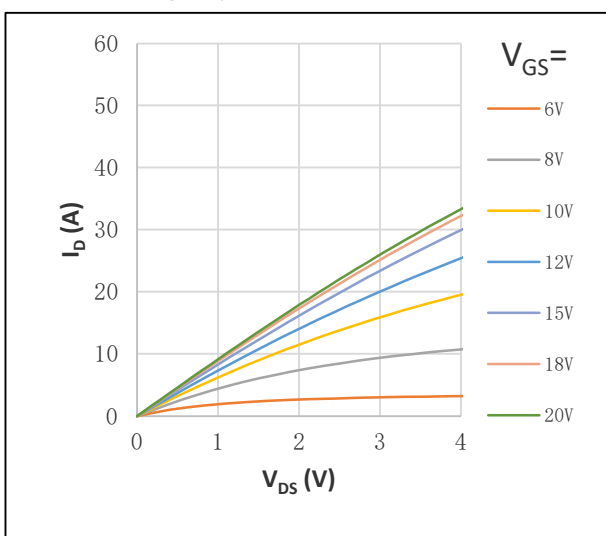
● Fig.3 Output characteristics: drain current as a function of drain-source voltage; Typical values; $T_j=-55^\circ\text{C}$



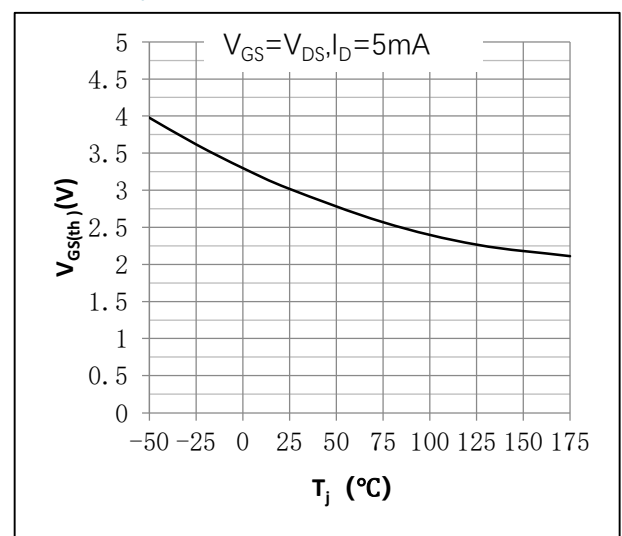
● Fig.4 Output characteristics: drain current as a function of drain-source voltage; Typical values; $T_j=25^\circ\text{C}$



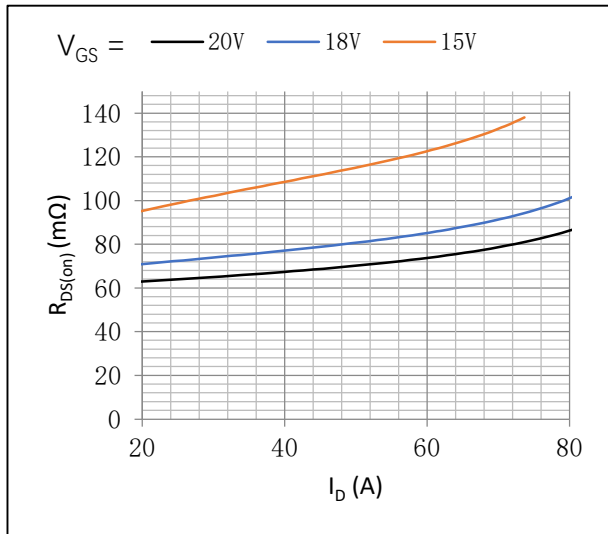
● Fig.5 Output characteristics: drain current as a function of drain-source voltage; Typical values; $T_j=175^\circ\text{C}$



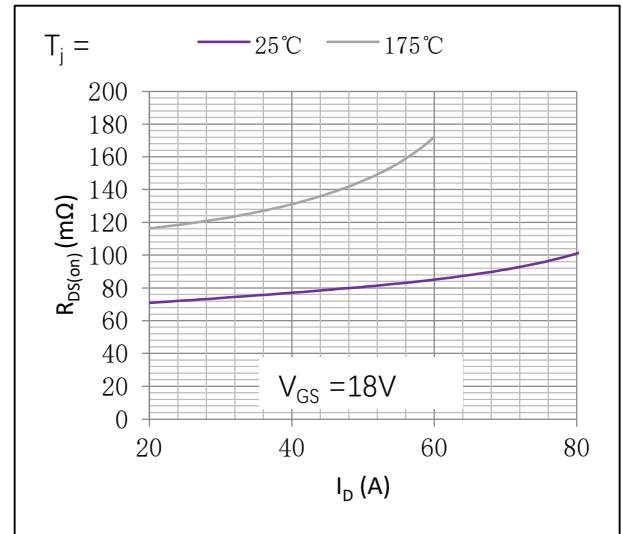
● Fig.6 Gate-source threshold voltage as a function of junction temperature; Typical values



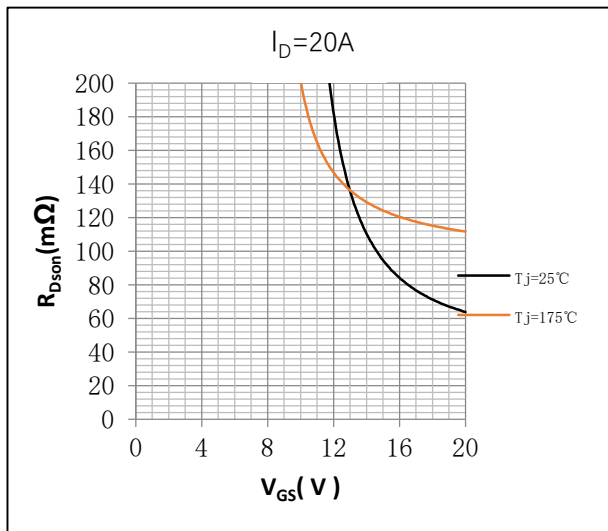
● Fig.7 Drain-source on-state resistance as a function of drain current; Typical values; $T_j=25^\circ\text{C}$



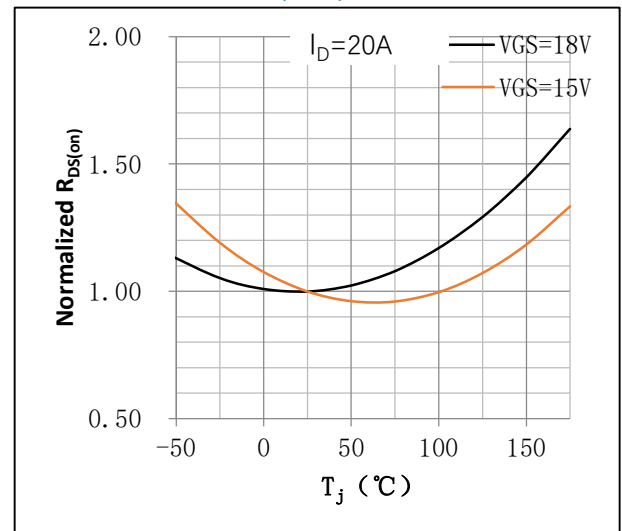
● Fig.8 Drain-source on-state resistance as a function of drain current; Typical values;



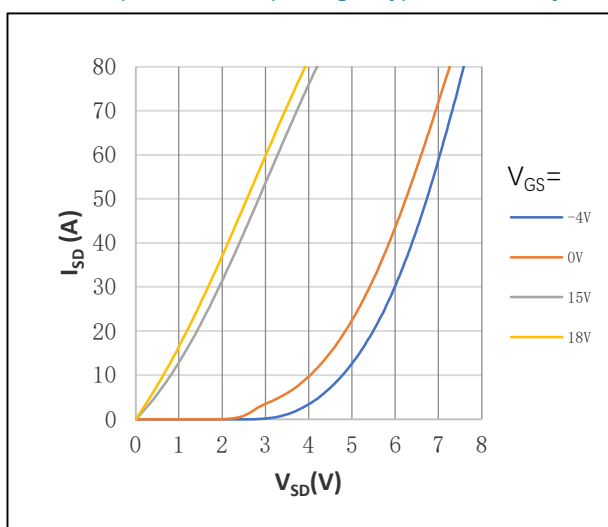
● Fig.9 Drain-source on-state resistance as a function of gate-source voltage; Typical values



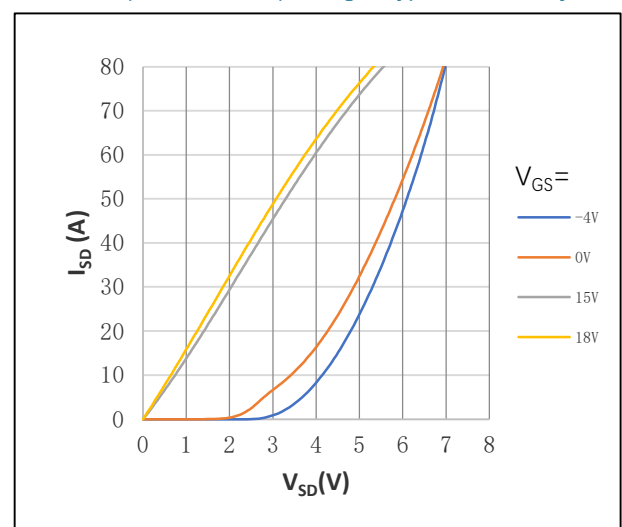
● Fig.10 Normalized drain-source on-state resistance factor as a function of junction temperature; Typical values Normalized On-Resistance = $R_{DS(on)}/R_{DS(on)}(25^\circ\text{C})$



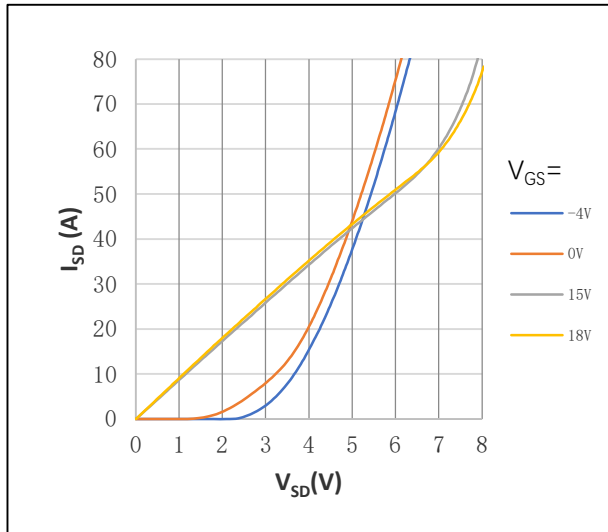
● Figure.11 Source (diode forward) current as a function of source-drain (diode forward) voltage; Typical values; $T_j=-55^\circ\text{C}$



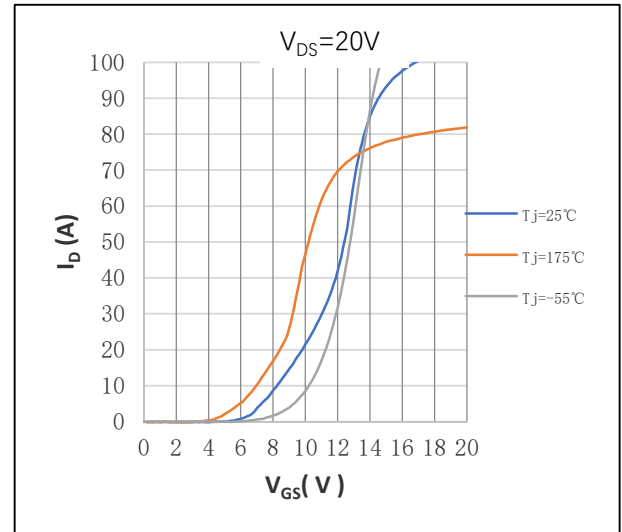
● Figure.12 Source (diode forward) current as a function of source-drain (diode forward) voltage; Typical values; $T_j=25^\circ\text{C}$



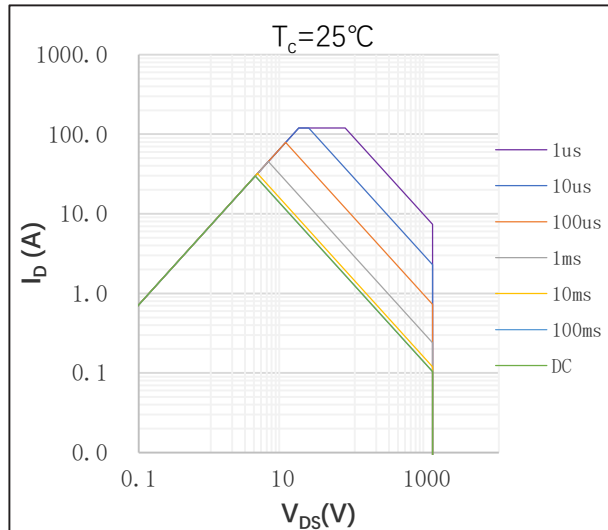
● Figure.13 Source (diode forward) current as a function of source-drain (diode forward) voltage; Typical values; $T_j=175^\circ\text{C}$



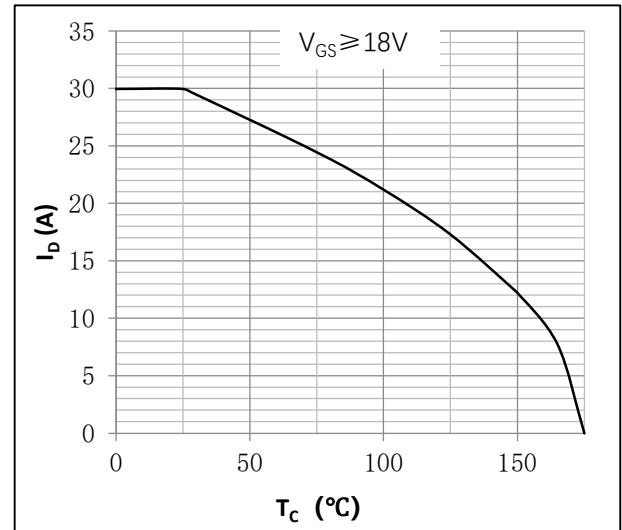
● Figure.14 Transfer characteristics: drain current as a function of gate-source voltage; Typical values



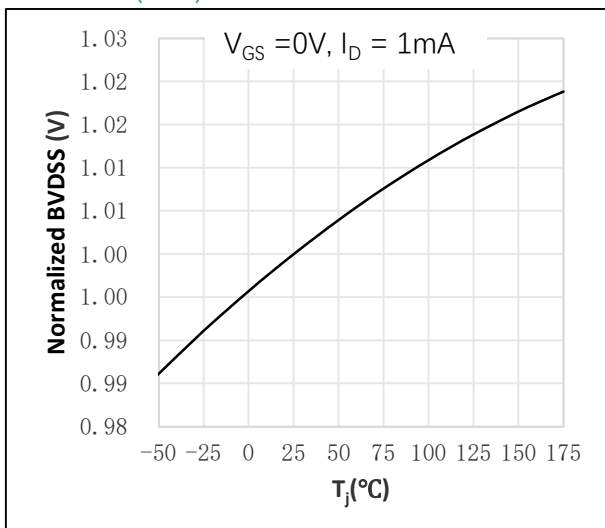
● Fig.15 Safe operating area: continuous and peak drain currents as a function of drain-source voltage; Calculative values



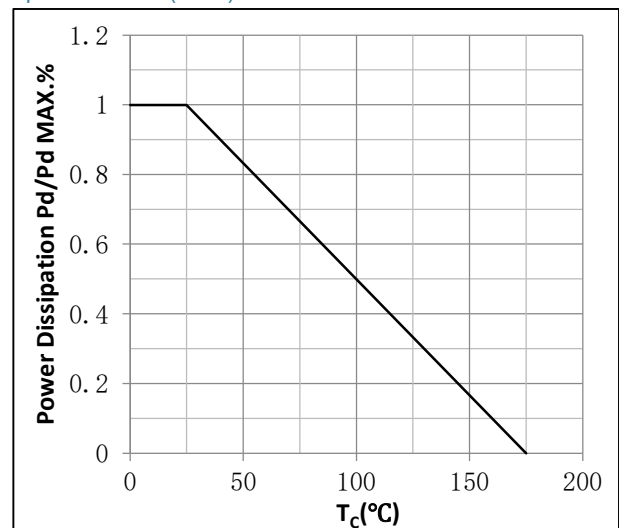
● Fig.16 Continuous drain current as a function of case temperature^①; Calculative values



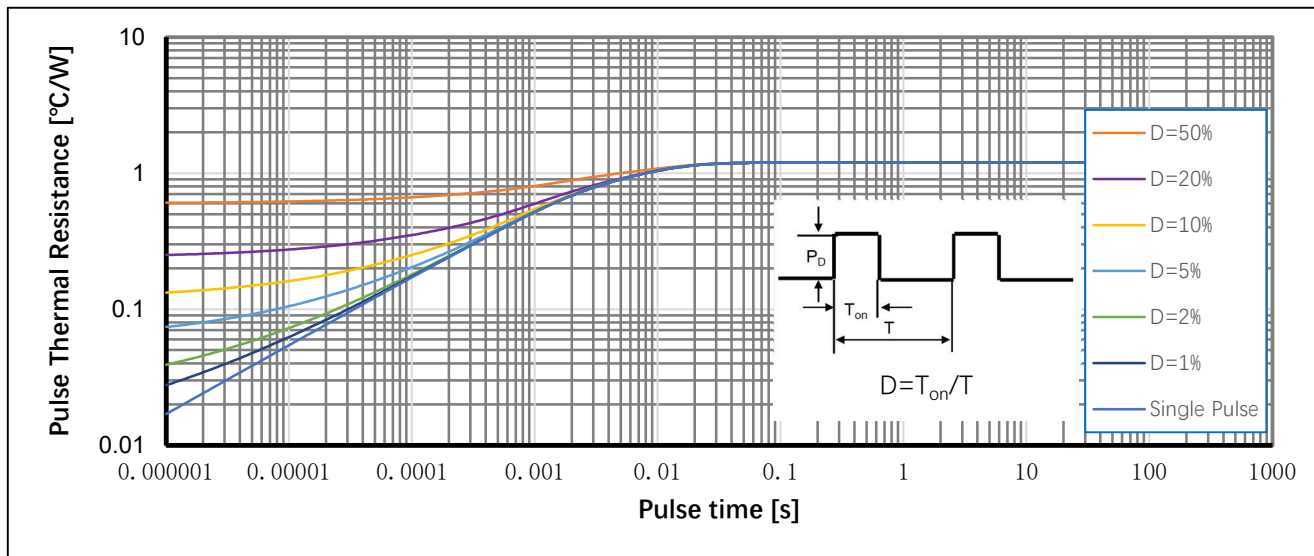
● Fig.17 Drain-source breakdown voltage as a function of junction temperature; Typical values Normalized $BV_{DSS} = BV_{DSS}/BV_{DSS}(25^\circ\text{C})$



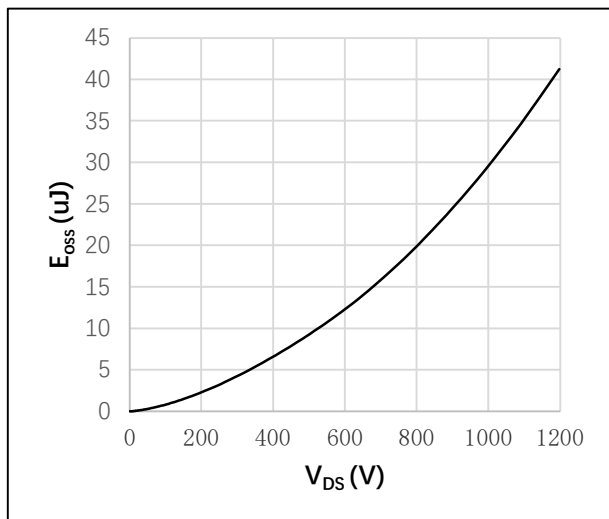
● Fig.18 Normalized total power dissipation as a function of case temperature; Calculative values Normalized Power Dissipation = $P_d/P_d(25^\circ\text{C})$



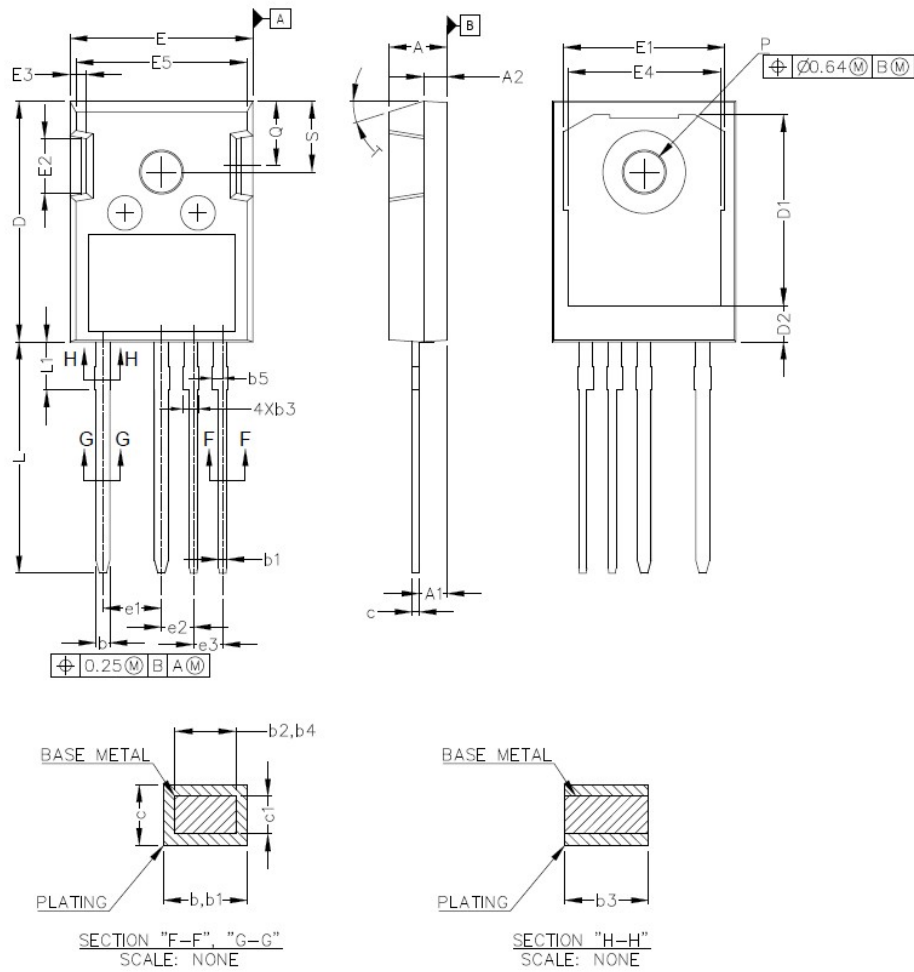
● Fig.19 Transient thermal impedance from junction to case as a function of pulse duration; max values



● Fig.20 Output capacitor stored energy as a function of drain-source voltage; Typical values; $T_j = 25^{\circ}\text{C}$



● Package Outline



SYM	MILLIMETERS	
	MIN	MAX
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b	1.10	1.30
b1	0.65	0.79
b2	1.10	1.25
b3	1.34	1.44
b4	0.65	0.74
b5	0.74	1.14
c	0.55	0.68
c1	0.55	0.65
D	20.80	21.10
D1	16.25	17.65
D2	2.95	3.35
E	15.75	16.13
E1	13.10	14.15
E2	4.32	5.10
E3	1.00	1.90
E4	12.38	13.43
E5	14.65	15.05
e1	5.08 BSC	
e2	2.79 BSC	
e3	2.54 BSC	
L	19.72	20.32
L1	3.97	4.37
øP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
T	17.5° REF.	

● Note

① Practically the current will be limited by PCB, thermal design and operating temperature. $V_{GS}=18V$.

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● Revision History

Version	Date	Change
A	2025/1/5	New